

PATENT

Attorney Docket No.: AMAT/7683/CMP/ECP/RKK

Express Mail No.: EV335470881US

ABSTRACT OF THE DISCLOSURE

Embodiments of the invention provide a method for removing contaminants from a plating bath contained in a weir-type plater during idle times. The method broadly includes positioning a lower portion of a substrate support assembly into the plating bath and rotating the substrate support assembly at a rotation rate of between about 1 rpm and about 60 rpm for between about 5 seconds and about 30 seconds to circulate the plating solution such that contaminants accumulating on the surface of the plating solution are urged to flow over a weir of the weir-type plater.

261860_1